

Title (en)

COOLING SYSTEM FOR USE WITH A POWER ELECTRONICS ASSEMBLY AND METHOD OF MANUFACTURING THEREOF

Title (de)

KÜHLSYSTEM ZUR VERWENDUNG MIT EINER LEISTUNGSELEKTRONIKANORDNUNG UND VERFAHREN ZUR HERSTELLUNG DAVON

Title (fr)

SYSTÈME DE REFRROIDISSEMENT DESTINÉ À ÊTRE UTILISÉ AVEC UN ENSEMBLE D'ÉLECTRONIQUE DE PUISSANCE ET SON PROCÉDÉ DE FABRICATION

Publication

EP 3003001 B1 20201104 (EN)

Application

EP 15186925 A 20150925

Priority

US 201414501683 A 20140930

Abstract (en)

[origin: EP3003001A2] A cooling system (206) for use with a power electronics assembly (200) comprising an array (202) of line-replaceable units (204) is provided. The cooling system (206) includes a first manifold (210) coupled in flow communication with the array (202) of line-replaceable units (204), and a fluid supply (208) coupled in flow communication with the first manifold (210). The fluid supply (208) is configured to channel cooling fluid towards the first manifold (210) such that the cooling fluid (208) is discharged towards the line-replaceable units (204) in the array (202) substantially simultaneously.

IPC 8 full level

B23P 15/26 (2006.01); **H05K 7/20** (2006.01)

CPC (source: EP US)

B23P 15/26 (2013.01 - US); **H05K 7/20681** (2013.01 - EP US)

Citation (examination)

US 2007209782 A1 20070913 - WYATT WILLIAM G [US], et al

Cited by

CN114096121A

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DOCDB simple family (publication)

EP 3003001 A2 20160406; **EP 3003001 A3 20160727**; **EP 3003001 B1 20201104**; BR 102015021691 A2 20160823; BR 102015021691 B1 20230314; CA 2898306 A1 20160330; CA 2898306 C 20180904; CN 105472943 A 20160406; CN 105472943 B 20190618; US 10576589 B2 20200303; US 2016095248 A1 20160331

DOCDB simple family (application)

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